US00D359028S

United States Patent [19]

Siegel et al.

[11] **Patent Number: Des. 359,028**

[45] **Date of Patent: ** Jun. 6, 1995**

---

[54] **SOCKETED INTEGRATED CIRCUIT PACKAGE**

[75] Inventors: **Harry M. Siegel**, Hurst; **Michael J. Hundt**, Double Oak; **Krishnan Kelappan**, Carrollton, all of Tex.

[73] Assignee: **SGS-Thomson Microelectronics, Inc.**, Carrollton, Tex.

[*] Notice: The portion of the term of this patent subsequent to May 30, 2009 has been disclaimed.

[**] Term: **14 Years**

[21] Appl. No.: **12,499**

[22] Filed: **Sep. 2, 1993**

[52] **U.S. Cl.** **D13/182**

[58] **Field of Search** D13/125, 182; 174/52.1, 174/52.4; 439/55, 70; 361/718, 820; 257/678, 723, 730, 731

[56] **References Cited**

U.S. PATENT DOCUMENTS

D. 82,797	12/1930	Cole	D13/125
D. 317,592	6/1991	Yoshizawa	D13/182
3,762,039	10/1973	Douglass et al.	174/52.4 X
3,891,898	6/1975	Damon	439/70 X
4,422,703	12/1983	Christensen et al.	439/55 X
4,868,349	9/1989	Chia	174/52.4
5,119,269	6/1992	Nakayama	361/820

Primary Examiner—Joel Sincavage
Attorney, Agent, or Firm—Rodney M. Anderson; Lisa K. Jorgenson; Richard K. Robinson

[57] **CLAIM**

The ornamental design for the socketed integrated circuit package, as shown and described.

DESCRIPTION

FIG. **1** is a perspective view of the integrated circuit package;

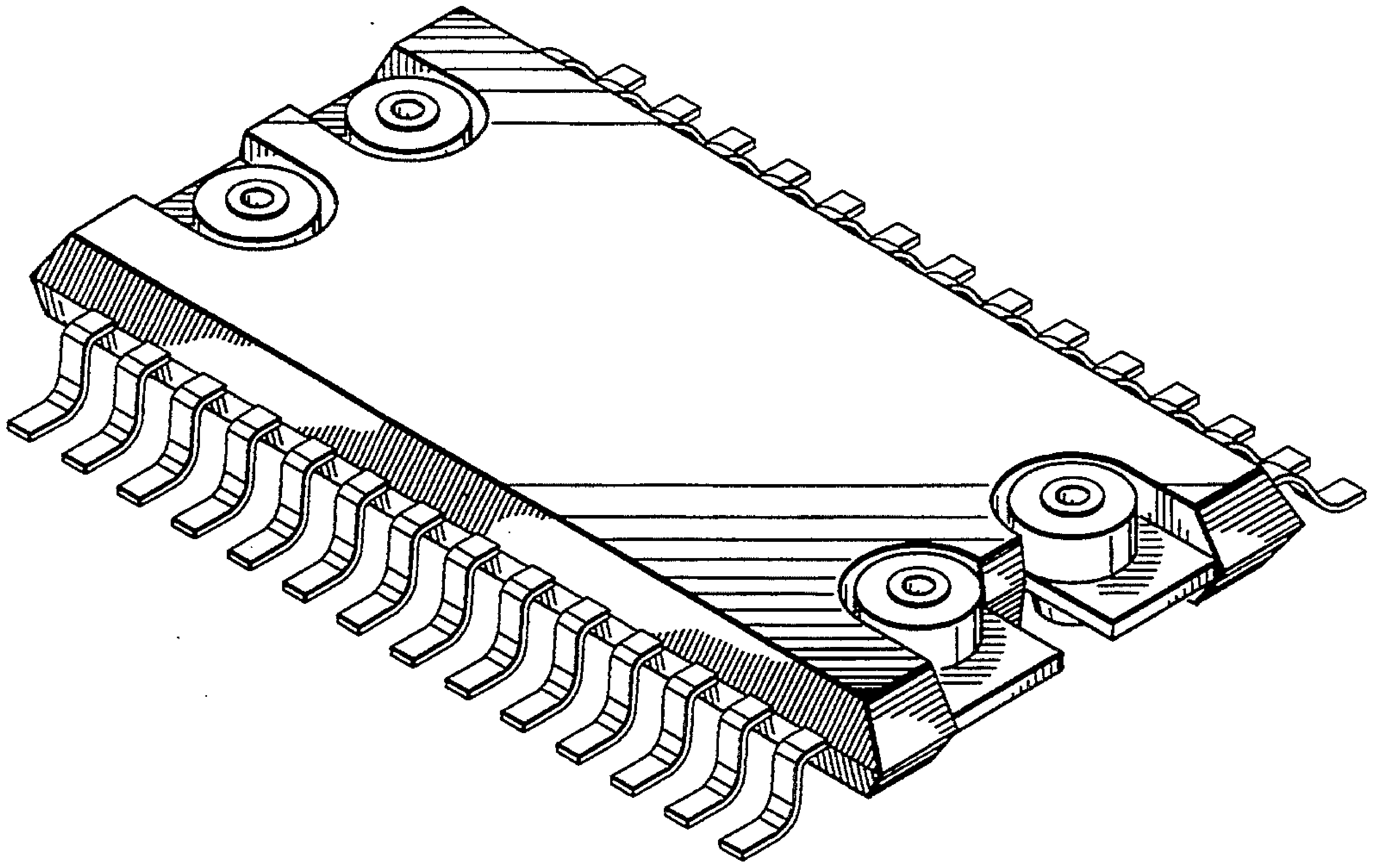
FIG. **2** is a side elevation view of the integrated circuit package;

FIG. **3** is an end elevation view of the integrated circuit package from its end nearer the lockout key;

FIG. **4** is an end elevation view of the integrated circuit package from its end opposite that from the lockout key;

FIG. **5** is a top plan view of the integrated circuit package; and,

FIG. **6** is a bottom plan view of the integrated circuit package.



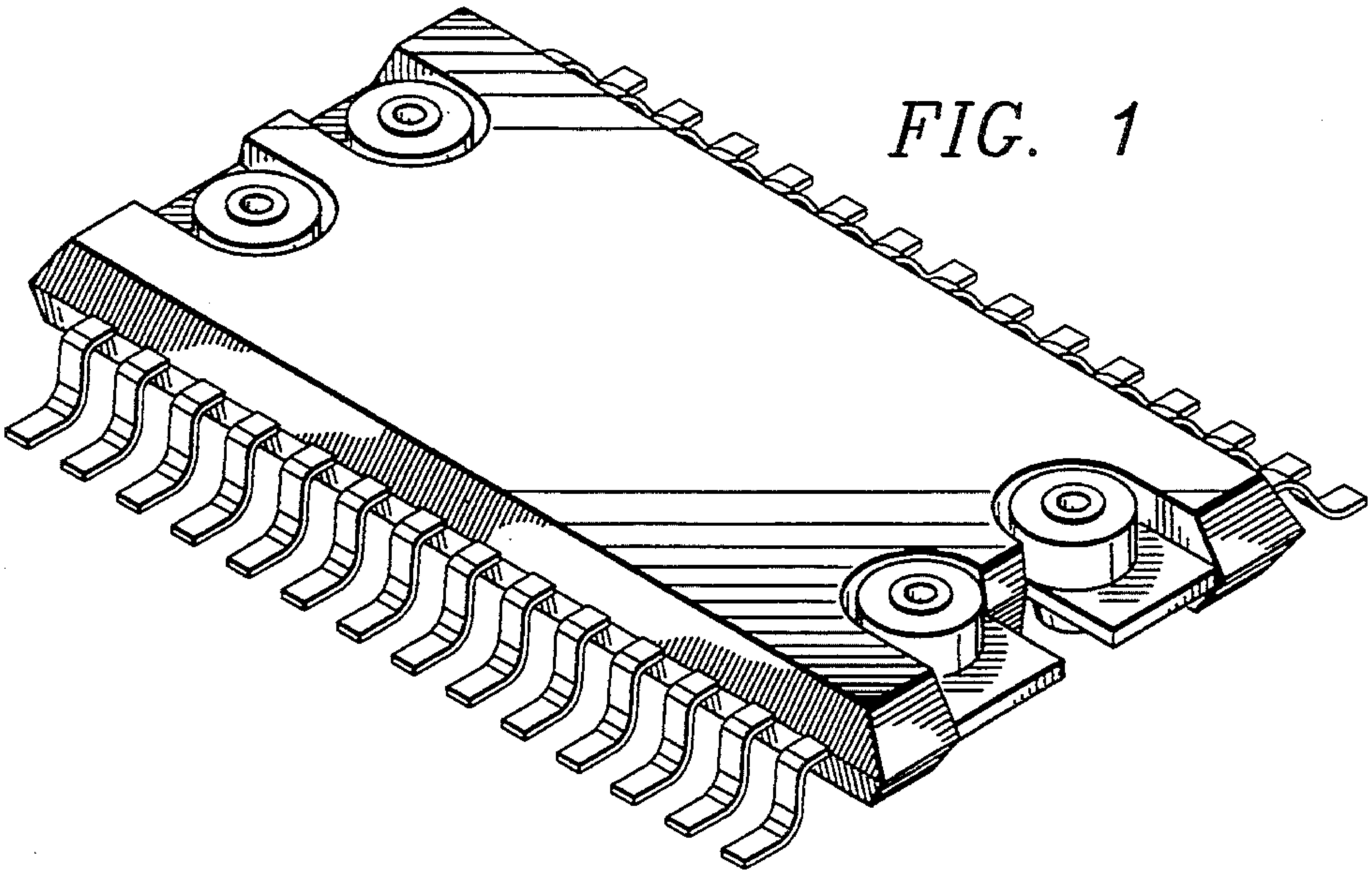


FIG. 1

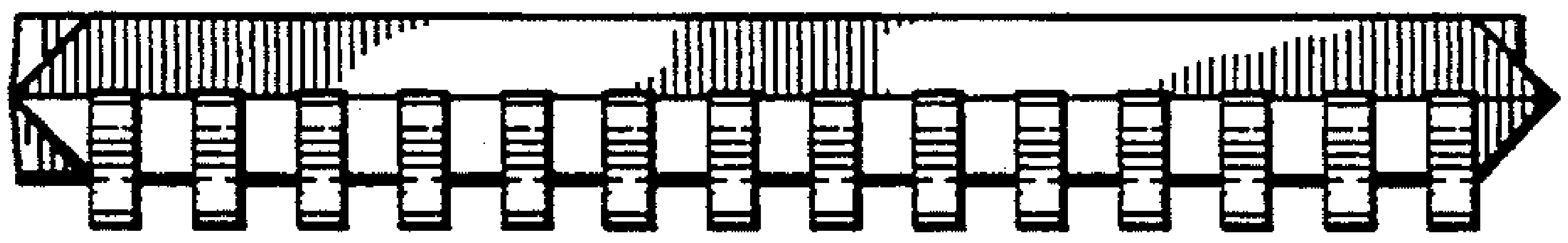


FIG. 2

FIG. 3

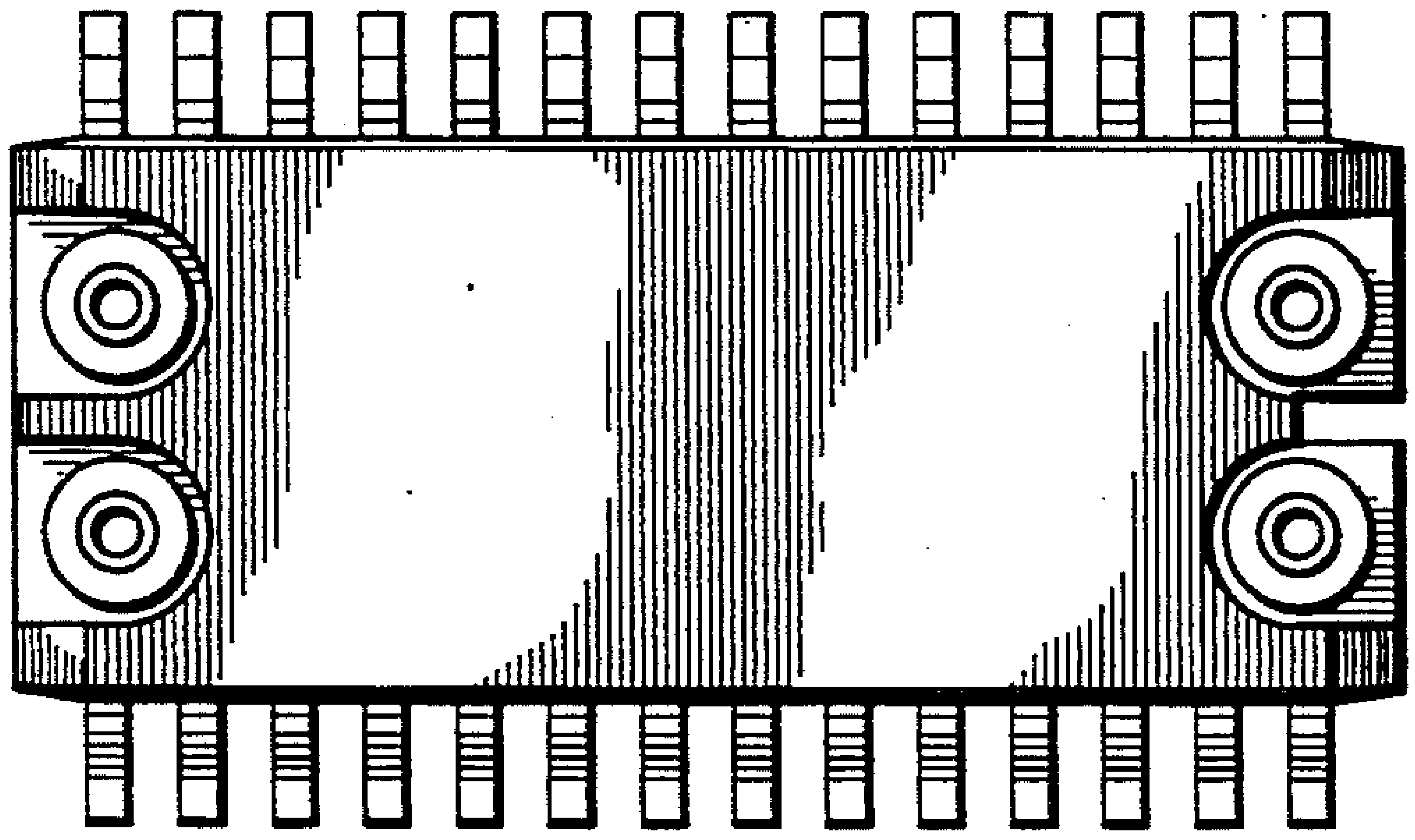


FIG. 5

FIG. 4

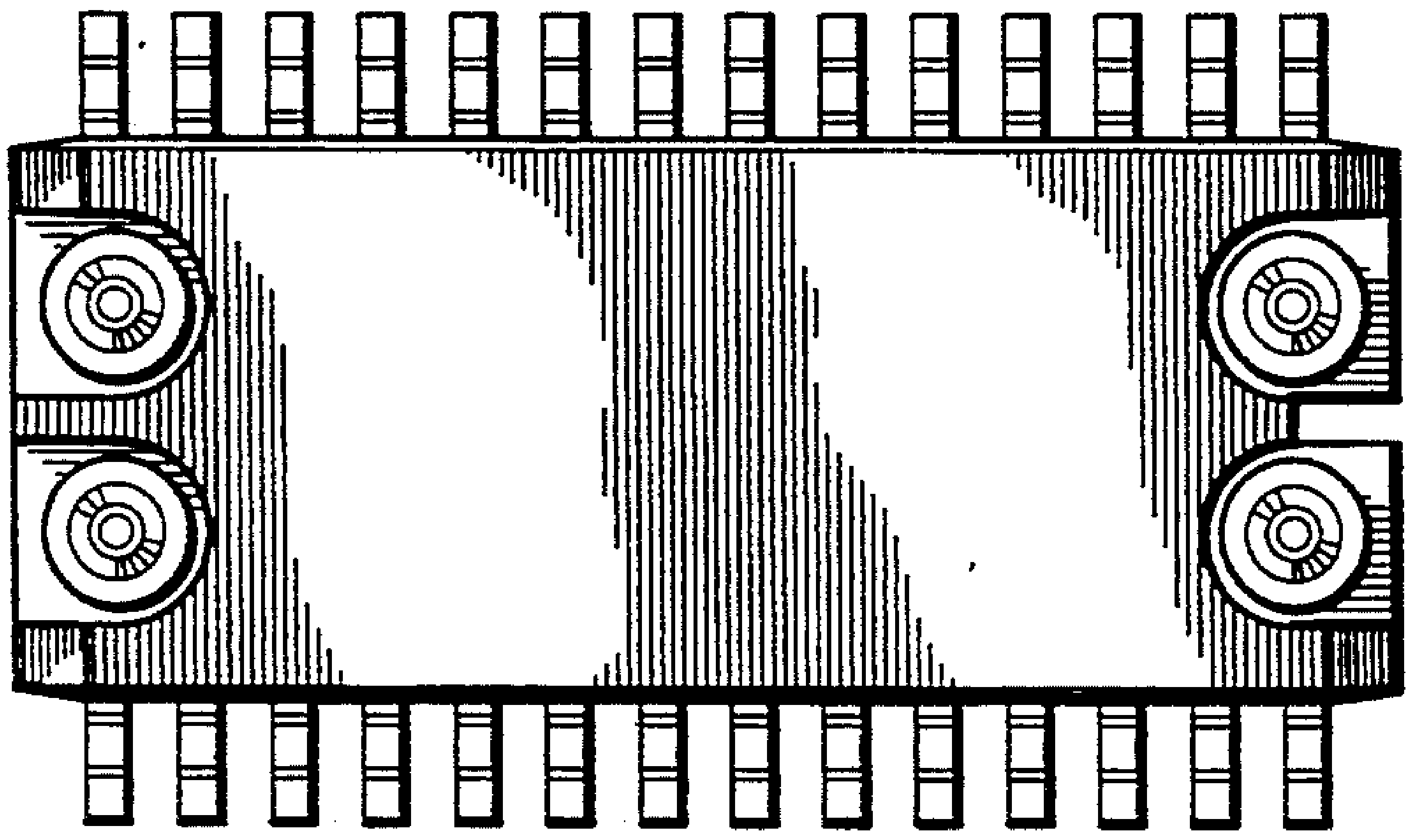


FIG. 6